

PCB LAYOUT \* - COMPONENT VIEW

## TECHNICAL CHARACTERISTICS

### MATERIAL

INSULATOR: LCP

FLAMABILITY RATING: UL94-V0

COLOR: BLUE

CONTACT MATERIAL: PHOSPHORE BRONZE

CONTACT TYPE: STAMPED

CONTACT PLATING: UNDERPLATE 1.27 to 2.54  $\mu\text{m}$  Ni

CONTACT AREA 0.76  $\mu\text{m}$  Gold

SOLDER TAIL AREA 2.54 to 5.08  $\mu\text{m}$  Matt Tin

SHIELDING: BRASS MATT TIN PLATED

### ENVIRONMENTAL

OPERATING TEMPERATURE: -20 up to +85°C

COMPLIANCE: RoHS & LEAD FREE AS PER DIRECTIVE 2002/95/EC

HALOGEN FREE COMPLIANT AS PER IEC 61249-2-21

### ELECTRICAL

CURRENT RATING:

- PIN 1 & PIN 4 (Vbus & corresponding ground PIN) 1.8A Max

- OTHER PINS 0.25 A Max

WORKING VOLTAGE: 30Vac

DIELECTRIC WITHSTANDING VOLTAGE: 100Vac/min

INSULATION RESISTANCE: > 100M $\Omega$

CONTACT RESISTANCE:

- PIN 1 & PIN 4: 30m $\Omega$  Max

- OTHER PINS: 50m $\Omega$  Max

### STANDARD

 CERTIFIED: E323964 / MODEL NUMBER 692121330100

### MECHANICAL

INSERTION FORCE: 35.0N Max

EXTRACTION FORCE: 10.0N min

QUALITY CLASS: 5000 MATING CYCLES



### SOLDERING

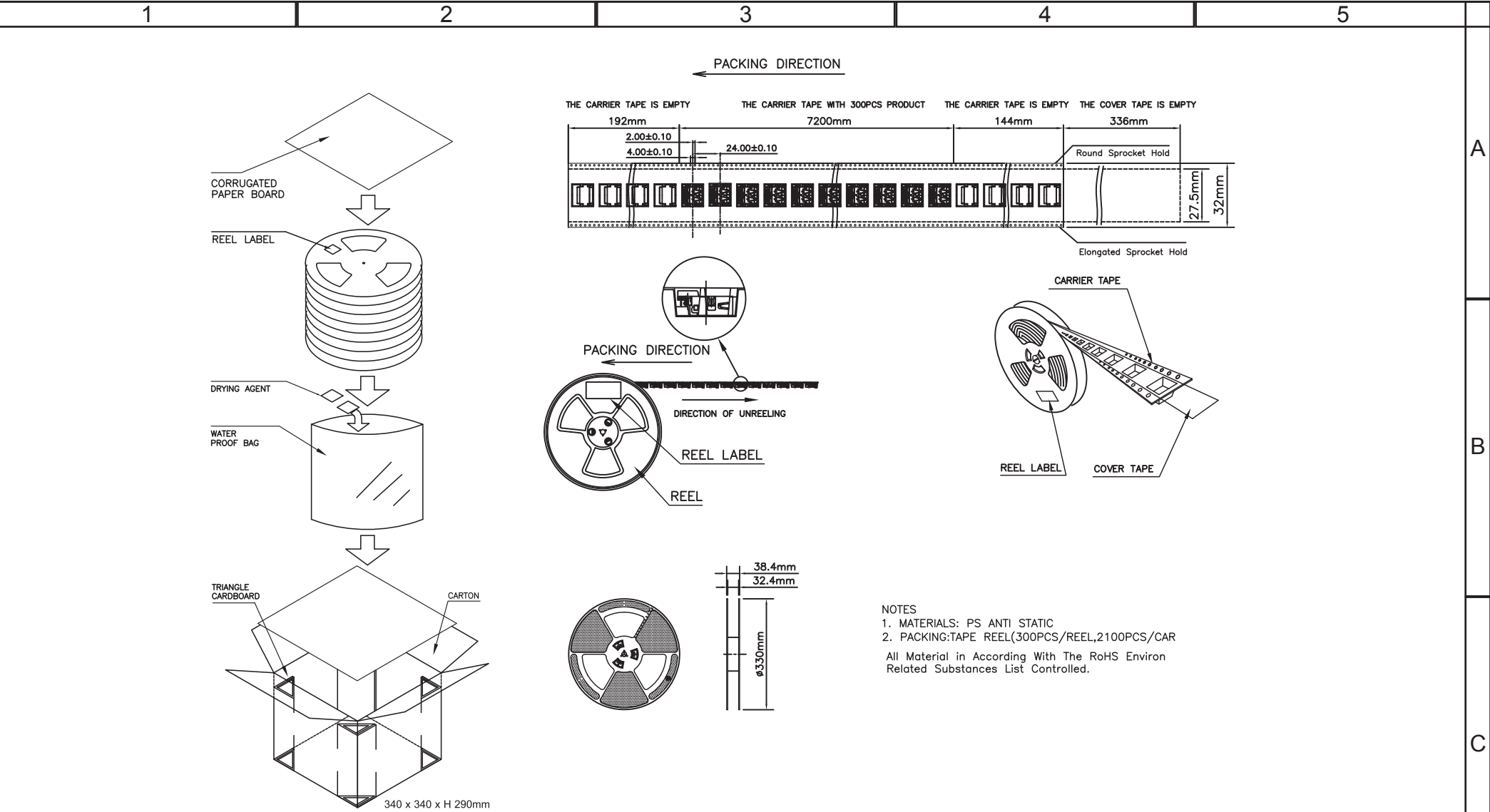
REFLOW PROCESS ONLY AS PER JEDEC J-STD-020D

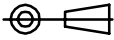

### PACKAGING

TAPE & REEL

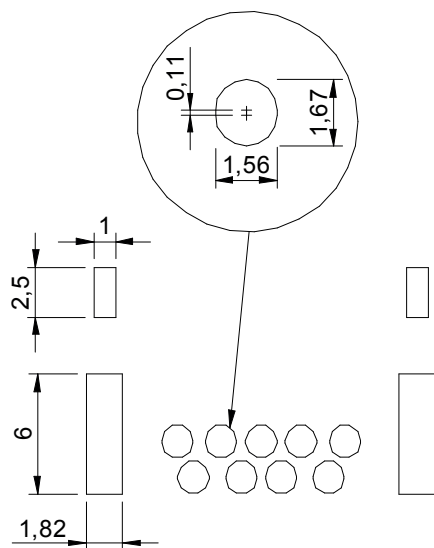
\* NOTE: THE RECOMMENDED PCB LAYOUT IS FOR AN OPTIMIZED RETENTION FORCE OF CONNECTOR ON PCB BUT IT IMPLIES INSERTION FORCE THAT A LOT OF PICK AND PLACE MACHINES ARE NOT ABLE TO HANDLE. THEREFORE IT MIGHT BE NECESSARY TO DRILL BIGGER HOLES FOR THE CLIPS. PLEASE CHECK THIS CAREFULLY.

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G				<div>PROJECTION:</div> <div></div>	<div>GENERAL TOLERANCE</div> <div>.X = <math>\pm</math> 0.2</div> <div>.XX = <math>\pm</math> 0.15</div>	<div></div> <div>WÜRTH ELEKTRONIK</div>		
F	12-AUG-13	DWG & CHARAC	QL					
E	09-NOV-11	STENCIL	GG					
D	21-SEP-11	NOTE	GG					
C	10-MAY-11	UL	GG	APPROVAL: RJ	UNIT: MM	DESCRIPTION: USB 3.0 REVERSE HORIZONTAL TYPE A WITH OFFSET 1.75 MM		SIZE <b>A4</b>
B	02-MAY-11	DIMENSION	GG		SCALE:			
A	04-AUG-10	PDF	JP		SHEET: 1/3	WERI PART NO: 692 121 330 100		
REV	DATE	FILE	BY		DRAW: JOE			



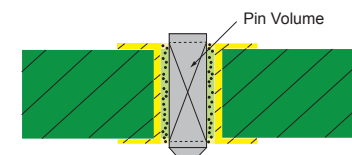
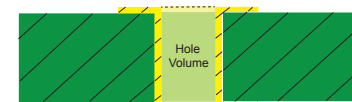
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G							
F							
E							
D				APPROVAL: RJ	UNIT: MM	DESCRIPTION: USB 3.0 REVERSE HORIZONTAL TYPE A WITH OFFSET 1.75 MM	
C					SCALE:		
B					SHEET: 2/3		
A					DRAW: JOE		
REV	DATE	FILE	BY				SIZE <b>A4</b>

### Stencil information for Through Hole Reflow soldering



### STENCIL LAYOUT \* - COMPONENT VIEW

PCB cross section

 Free volume for solder paste

### Theoretical Formula for Through Hole pins

$$\text{Volume of the stencil aperture} = (\text{Hole volume} - \text{Pin volume}) \times 2$$

or

$$\text{Volume of solder paste} = (\text{Hole volume} - \text{Pin volume}) \times 2$$



## Stencil

Stencil Thickness: 150  $\mu\text{m}$

PCB

PCB thickness: 1.6mm

\* NOTE: SEE PCB LAYOUT PAGE 1/3 FOR MISSING DIMENSIONS

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F							
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B					SCALE:		
A					SHEET: 3/3		
REV	DATE	FILE	BY		DRAW: JOE		